

Product Change Notification / RMES-06ZXIX068

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06-Dec-2021

Product Category:

FPGA Configuration Memory

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4241.001 Initial Notice: Qualification of G700LS molding compound for AT17LV002-10SU catalog part number (CPN) available in 20L SOIC package (300 mils) at ANAP assembly site.

Affected CPNs:

RMES-06ZXIX068_Affected_CPN_12062021.pdf RMES-06ZXIX068_Affected_CPN_12062021.csv

Notification Text:

PCN Status:Initial notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:Qualification of G700LS molding compound for AT17LV002-10SU catalog part number (CPN) available in 20L SOIC package (300 mils) at ANAP assembly site

Pre and Post Change Summary:

	Pre Change	Post Change				
Assembly Location	Amkor Technology Philippine (P1/P2), INC. / ANAP	Amkor Technology Philippine (P1/P2), INC. / ANAP				

Wire material	Au	Au			
Die attach material	8290 8290				
Molding compound material	G600	G700LS			
Lead frame material	C194	C194			
Lead Lock	Yes	Yes			
Lead frame treatment	Non-Roughened	Roughened			
Lead frame Comparison	Please see attached pre and post change summary				

Impacts to Data Sheet:None

Change Impact:None

Reason for Change:To improve productivity by qualifying G700LS molding compound **Change Implementation Status:**In Progress

Estimated Qualification Completion Date:

January 2022

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date quided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	December 2021		January 2022					2			
Workweek	4 9	5 0	5 1	5 2	^	0 1	0 2	03	0 4	0 5	06
Initial PCN Issue Date		Х									
Qual Report Availability											Х
Final PCN Issue Date											Χ

Method to Identify Change: Traceability code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History:

December 06, 2021: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_RMES-06ZXIX068_Qual_Plan.pdf PCN_RMES-06ZXIX068_Pre and Post_Change Summary.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.	
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If you wish to <u>change your PCN profile</u> , <u>including opt out</u> , please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.	
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Affected Catalog Part Numbers (CPN)
AT17LV002-10SU
Date: Monday, December 06, 2021